

MA4SD10

Silicon epitaxial planar type

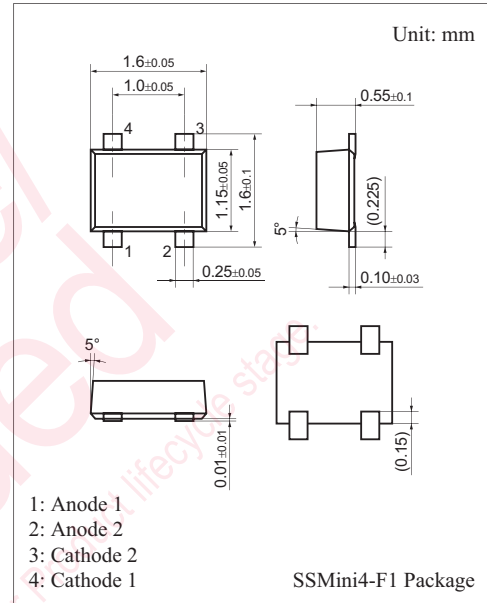
For super-high-speed switching circuits

■ Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Low forward voltage V_F

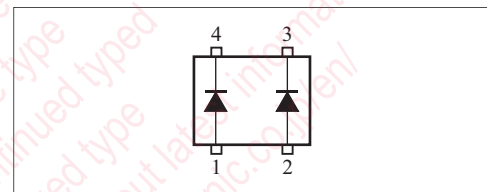
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V_{RRM}	20	V
Forward current (Average)	Single	200	mA
	Double	150	
Peak forward current	Single	300	mA
	Double	225	
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



Marking Symbol: M2A

Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

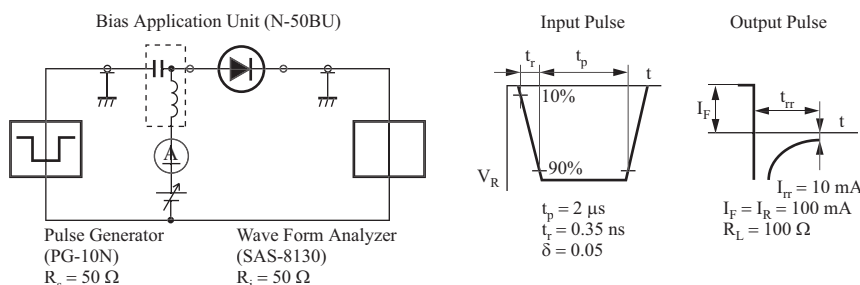
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 5 \text{ mA}$			0.27	V
	V_{F2}	$I_F = 100 \text{ mA}$			0.40	
	V_{F3}	$I_F = 200 \text{ mA}$			0.47	
Reverse current	I_R	$V_R = 10 \text{ V}$			20	μA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		25		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{tr} = 10 \text{ mA}$ $R_L = 100 \Omega$		3		ns

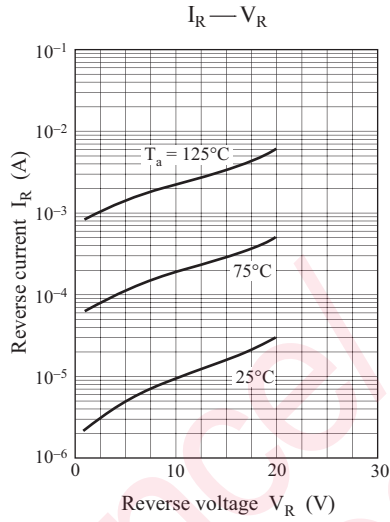
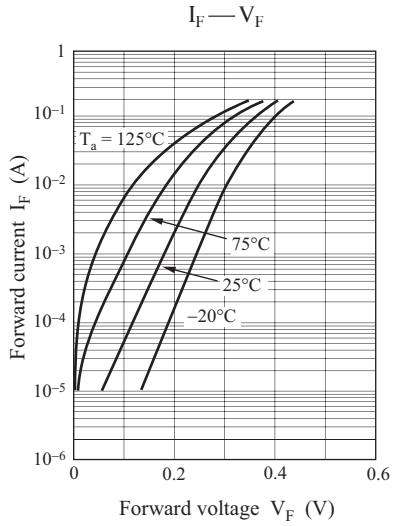
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 250 MHz

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *: t_{rr} measurement circuit





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